PRODUCT LINE-UP

TOKYO ELECTRON产品介绍2026

CLEAN TRACK™ LITHIUS Pro™ Z

制造：TOKYO ELECTRON九州
Mfg:Tokyo Electron Kyushu

Features

- Low particle wafer transfer system ▪ 低颗粒晶圆传输系统
- Improved Overall Equipment Efficiency (OEE) for litho cells ▪ 提升整体光刻系统的设备综合效率（OEE）
- Reduced Cost of Chemicals (CoC) and energy usage ▪ 大幅削减化学制剂成本并实现节能化

Applications

- All lithography processes ▪ 适用光刻全制程

CLEAN TRACK™ LITHIUS Pro™ AP

制造：TOKYO ELECTRON九州
Mfg:Tokyo Electron Kyushu

Features

High throughput/Small footprint	产能高/占地面积少
Improved OEE (Overall Equipment Efficiency)	提升OEE（Overall Equipment Efficiency）
Special wafer support (warped wafer, glass wafer, bonded wafer etc.)	支持处理特殊晶圆（翘曲晶圆、玻璃晶圆、键合晶圆等）

Applications

Advanced packaging process	先进封装工艺
Polyimide process	聚酰亚胺工艺
SOG/SOD coating process	SOG/SOD涂布工艺

单片清洗设备
Single Wafer Cleaning System

CELLESTA™ -*i*

制造：TOKYO ELECTRON九州
Mfg:Tokyo Electron Kyushu

Features

High throughput of up to 1,000 wafers per hour	高产能（最高每小时1,000片）
Damage-free physical cleaning using new atomizing spray	采用新型喷头，实现无损伤物理清洗
Unique drying technology that controls watermarks and pattern damage	采用独家干燥技术，有效防止水痕与图形损坏的产生
Independent control of process environment in each chamber	独立控制各反应腔室内的工艺环境
Spinner technology compatible with various process chemistries	兼容各种工艺化学制剂的旋涂技术

Applications

Pre-diffusion and pre-CVD cleaning	扩散和沉积的前清洗
Post-etch cleaning	刻蚀后的清洗
Wet etch	湿法刻蚀
Backside and bevel cleaning	晶圆背面・晶边的清洗
Post-etch polymer removal	刻蚀后聚合物的清洗

自动湿法清洗设备
Auto Wet Station

EXPEDIUS™-*i*

制造：TOKYO ELECTRON九州
Mfg:Tokyo Electron Kyushu

Features

Transfer system with throughput of 1,000wph	每小时1,000片的传输能力
Short-time resist stripping	短时间光刻胶剥离
Highly selective and stable process for 3D NAND SiN etch process	高选择性和稳定的3D NAND氮化硅刻蚀工艺
New nozzle concept for etch uniformity Improvement (WIW, WTW)	采用全新喷头设计，提升刻蚀均一性（WIW、WTW）
Equipped with a stacked dual chamber dryer (SD2)	搭载一个全新的SD2（堆叠式双腔干燥机）

Applications

Pre-diffusion and pre-CVD cleaning	扩散和沉积前的清洗
Post-etch cleaning and resist strip	刻蚀后的清洗/光刻胶剥离
Wet-etch (SiN etch, W recess, Poly Si etch)	湿法刻蚀（氮化硅刻蚀、W凹槽、多晶硅刻蚀）
Rework and recycle	再加工/再循环

等离子蚀刻设备
Plasma Etch System

Episode™ UL

制造：TOKYO ELECTRON宫城
Mfg:Tokyo Electron Miyagi

Features

Maximize space utilization with a flexible arrangement of up to 12 chambers
Make your manufacturing smarter with:
- Multiple sensors for tool health monitoring
- EtherCAT* for high speed process control
- AI/Machine Learning for Big Data analysis
- Auto calibration for tool matching

最多支持12个处理各类应用的工艺反应腔室和后处理反应腔室，实现制造过程的更智能化：
- 为设备实现稳定运行配备多个传感器
- 通过EtherCAT*实现高速的监控与工艺控制
- 通过AI/机器学习进行大数据分析
- 通过自动化校准实现设备匹配

*EtherCAT: Ethernet for Control Automation Technology（工业用开放网络）

*EtherCAT属于Beckhoff Automation GmbH的注册商标。
*EtherCAT is a registered trademark of Beckhoff Automation GmbH.

Applications

Dielectric	绝缘膜
Conductor	硅
Reactive Ion Etch	反应离子刻蚀

等离子蚀刻设备
Plasma Etch System

Tactras™

制造：TOKYO ELECTRON宫城
Mfg:Tokyo Electron Miyagi

Features

Support up to 6 process chambers and after treatment chambers	最多可支持6个工艺反应腔室和后处理反应腔室
Robust design to minimize offset in machine-to-machine and chamber-to-chamber	采用极大限度地减少设备之间、反应腔室之间偏移的优化设计
Particle reduction technology	颗粒降低技术

Applications

Dielectric	绝缘膜
Conductor	硅
Reactive Ion Etch	反应离子刻蚀

气相化学蚀刻设备
Gas Chemical Etch System

Certas LEAGA™

制造：TOKYO ELECTRON TECHNOLOGY SOLUTIONS
Mfg:Tokyo Electron Technology Solutions

Features

- Higher productivity with flexible module layout concept — 灵活的的模组布局，实现更高生产效率
- Selective etch of various oxide films — 各种氧化膜的高选择性刻蚀
- Good controllability of micro-loading and etch profile — 减少稀密图形的负载，实现刻蚀形貌可控

Applications

- Dielectric — 绝缘膜
- Chemical dry etch — 化学干法刻蚀

热处理成膜设备

Thermal Processing System

TELINDY PLUS™

制造：TOKYO ELECTRON TECHNOLOGY SOLUTIONS
Mfg:Tokyo Electron Technology Solutions

Features

Batch ALD process to achieve high step coverage and high productivity	批量原子层沉积工艺：兼顾高台阶覆盖率与高生产率
Seed technology to achieve thin film controllability	种子层技术：提升CVD膜的薄膜可控性
High-speed robotics	高速机械手臂
Dry cleaning technology for particle reduction	干法清洗技术：降低颗粒
31% reduction of energy consumption per wafer by decreasing L/L N2 flow rate and by higher throughput（SEMI S23 conversion, compared to TELINDY™）	与TELINDY™相比，单片晶圆的能耗降低31%，具有更高的生产效率（按SEMI S23标准换算）

Applications

Oxide/Anneal/CVD/ALD	成膜设备（氧化物/退火/化学气相沉积/原子层沉积）

磁场热处理设备的相关介绍，请参见我司网站
For magnetic annealing, please visit our website
www.tel.com/product/#all

原子层沉积设备
Atomic Layer Deposition System

NT333™

制造：TOKYO ELECTRON TECHNOLOGY SOLUTIONS
Mfg:Tokyo Electron Technology Solutions

Features

Thickness controllability at the monolayer level through sufficient gas adsorption and oxidation	通过充分的气体吸附与氧化作用，实现原子级膜厚可控性
High quality film deposition by taking quality improvement steps into ALD cycles	在原子层沉积循环过程中采取品质改善措施，实现高品质薄膜沉积
SiO_2 film deposited in low temperature regions (≤400˚C) has comparable HF etch resistance and leakage performance to thermal oxide	在低温区域（400°C以下）沉积的二氧化硅薄膜具有与热氧化物相当的耐氟化氢刻蚀和防漏性能
Enabling excellent film property uniformity required for high aspect ratio structures on 3D NAND devices at high temperatures (760˚C)	实现在高温区域（760°C）下的3D NAND器件中高深宽比结构所需的卓越的薄膜厚度一致性

Applications

Various and dielectric films Thermal and plasma configuration	各种电介质薄膜——热/等离子结构

单片成膜设备
Single Wafer Deposition System

Episode™ 1

制造：TOKYO ELECTRON TECHNOLOGY SOLUTIONS
Mfg:Tokyo Electron Technology Solutions

Features

Support continuous execution of multiple processes by up to 8 process modules	最多可配置8个工艺模组，支持多个工艺持续执行
Reduced contact resistance in advanced logic devices by combining OPTCURE™ and ORTAS™ process modules	通过OPTCURE™与ORTAS™工艺模组的组合，降低接触电阻
Enhanced data collection and edge data processing systems improve equipment availability and engineering efficiency	采用增强型数据采集与边缘信息处理系统，辅助提升设备利用率与工程师作业效率

Applications

Logic contact	逻辑接触

单片成膜设备
Single Wafer Deposition System

Episode™ 2 DMR

制造：TOKYO ELECTRON TECHNOLOGY SOLUTIONS
Mfg:Tokyo Electron Technology Solutions

Features

High throughput and minimal footprint by simultaneously transferring two wafers	通过同时传送两片晶圆，实现生产性能提升和占用空间减小
DMR (Duo Matched Reactor) concept enables simultaneous deposition of two wafers	基于DMR（双重匹配反应器）设计，可同时沉积两片晶圆
Succeeding the Triase+™ EX-II™ series, also offers coping with future devices and higher aspect ratios Enhanced data collection and edge data processing systems improve equipment availability and engineering efficiency	作为Triase+™ EX - II™系列的下一代产品，能够满足未来器件及更高深宽比的需求 采用增强型数据采集与边缘信息处理系统，辅助提升设备利用率与工程师作业效率

Applications

Capacitor electrode	电容电极
Word line TiN	字线TiN
Barrier metal	金属阻挡层

物理气相沉积设备
PVD System

LEXIA™-EX

制造：TOKYO ELECTRON TECHNOLOGY SOLUTIONS
Mfg:Tokyo Electron Technology Solutions

Features

Scalable platform concept inherited from EXIM™	沿用EXIM™的可扩展平台
Footprint reduction	省占用空间
High throughput	高产能
Ultra high vacuum design	超高真空设计
Excellent uniformity	卓越的膜均一性
Best in class CoC and CoO	优异的耗材成本和运营成本控制

Applications

Multilayer	多层膜
Hardmask	硬掩模
Logic functional film	逻辑功能性膜

晶圆探针台
Wafer Prober

Prexa™

制造：TOKYO ELECTRON TECHNOLOGY SOLUTIONS
Mfg:Tokyo Electron Technology Solutions

Features

English	中文
Automation of operations	自动化操作
High accuracy contact	高精确定位
High speed inspection	高速检测
New software structure	全新软件构架
Advanced safety functions for probe card and wafer	适用探针卡和晶圆的先端安全功能
UTCS (Uniformize Temperature Control System)	UTCS (Uniformize Temperature Control System)

Applications

English	中文
High heat generating device (HPC, GPU, Memory etc.)	高发热产品（HPC、GPU、存储器等）
Small die and fine pitch probing	窄间距/小pad测试
High pin count and high multi-site SoC and memory	多探针/多die同测的测试
Full wafer testing	全晶圆测试
Low noise parametric probing	低噪声参数测量

晶圆探针台
Wafer Prober

WDF™ 12DP+

制造： TOKYO ELECTRON TECHNOLOGY SOLUTIONS
Mfg:Tokyo Electron Technology Solutions

Features

Fully automatic dicing frame and standard wafer handling	全自动划割框架及标准化晶圆处理
Change over kit to easily switch between 300mm and 200mm	通过组件转换， 可在300mm和200mm间轻松切换
N-Shot alignment for high accuracy, parallelism probing for diced wafer	通过N-Shot对准技术， 实现切片晶圆的高精度和并行探测
Improved system cleanliness and ESD*	改善设备洁净度与静电释放
TEL standard prober application software	支持TEL标准晶圆探针设备的应用软件

Applications

Post dicing test for KGD*, RMA*	提供KGD*与RMA*的切割后检验
Advanced package test capability (WLP, FOWLP, Panel level package)	先进封装测试能力（WLP、FOWLP、面板级封装）
Test for thin wafer, multiple PCB, strip frames on dicing frames	针对薄晶圆、多PCB、 strip frames on dicing frames进行测试

*ESD: Electro Static Discharge *KGD: Known Good Die *RMA: Return Merchandise Authorization

堆叠探针台
Multi-Cell Test System

Cellcia™

制造：TOKYO ELECTRON TECHNOLOGY SOLUTIONS
Mfg:Tokyo Electron Technology Solutions

Features

Asynchronous and simultaneous test in each cell	对每个单元进行异步和同步测试
Ultra-compact footprint by multi-layer system structure	采用多层系统结构实现占地面积大幅减少
TAT reduction by simultaneous test in multiple cells	对多个单元进行同步测试，大幅缩短TAT（周转时间）
Highly reliable front-end equipment wafer robot technology	采用了高可靠性的前道设备晶圆机器人技术

Applications

300mm memory device	300mm存储器件
Full wafer contact	全晶圆测试

Synapse™ V / Synapse™ Z Plus

制造：TOKYO ELECTRON九州
Mfg:Tokyo Electron Kyushu

Features

Designed for high volume manufacturing	为大规模量产而设计
Realizes the entire temporary bonding process	实现整个临时键合工艺
Achieves debonding and handling of wafer with 35um or greater thickness	实现35μm或更厚晶圆的解键合和处理
Establishes room temperature debonding process	建立室温解键合工艺

Applications

Temporary bonding and debonding for TSV manufacturing	用于TSV制造的临时键合和解键合
Wafer permanent bonding	晶圆永久键合

晶圆键合装置
Wafer Bonding System

Synapse™ Si

制造：TOKYO ELECTRON九州
Mfg:Tokyo Electron Kyushu

Features

Designed for high volume manufacturing	为大规模量产而设计
High availability for production	高度适用生产
Excellent alignment accuracy	卓越的校准精度
Realized high volume manufacturing with Cu hybrid wafer bonding technology	采用铜混键合技术实现量产化

Applications

Any application requires fusion bonding	适用于所有需要熔融键合的应用
Any application requires Cu hybrid wafer bonding device	适用所有需要铜混键合的应用

激光切边设备
Laser Edge Trimming System

Ulucus™ L

制造：TOKYO ELECTRON九州
Mfg:Tokyo Electron Kyushu

Features

English	中文
Designed for high volume manufacturing	为大规模量产而设计
Excellent trimming accuracy	高修整精度
Latest platform utilizing clean technology from the front-end process, with the integration of laser technology	集成先端激光技术的前道超净技术新型平台
Ensured reduction in DIW* consumption, dust emissions, and waste water discharges	确保去离子水耗量、粉尘排放与废水排放的减少

＊Deionized water

Applications

English	中文
300mm wafer to wafer fusion bonding device	采用300mm晶圆到晶圆熔融键合工艺的器件
300mm wafer to wafer Cu hybrid bonding device	采用300mm晶圆到晶圆铜混键合工艺的器件

激光剥离设备
Extreme Laser Lift Off System

Ulucus™ LX

制造：TOKYO ELECTRON九州
Mfg:Tokyo Electron Kyushu

Features

Designed for high volume manufacturing	为大规模量产而设计
Latest platform utilizing clean technology from the front-end process, with the integration of laser technology	采用配备前道工艺的清洗技术的最新平台与激光技术
Realize separation of top silicon substrate from Fusion/Cu hybrid bonded silicon substrate using laser technology	采用激光技术，实现永久性键合晶圆的基板分离
Technology for reducing environmental impact by replacing existing thinning processes after Fusion/Cu hybrid bonding	引入替代晶圆永久键合后的减薄工艺的技术，减少对环境的影响

Applications

300mm Wafer to Wafer Fusion/Cu hybrid bonding device	采用300mm晶圆到晶圆熔融键合/铜混键合工艺的器件
Die to wafer Fusion/Cu hybrid bonding device	采用芯片到晶圆熔融键合/铜混键合工艺的器件

晶圆减薄设备
Wafer Thinning System

Ulucus™ G

制造：TOKYO ELECTRON九州
Mfg:Tokyo Electron Kyushu

Features

Wafer thinning system for 300mm wafer fabrication	适用于300mm晶圆制造工艺的晶圆减薄设备
Integrating the advanced grinding technology into the latest platform of front-end's super clean technology	集成先端研磨技术的前道超净技术新型平台
Single-wafer processing units allow control over the quality of each wafer	单晶圆处理单元可对每张晶圆进行品控
High-quality processing of both sides of wafers	对晶圆正反面均可进行高质量处理

Applications

300mm wafer fabrication	300mm晶圆制造

批量喷淋清洗设备
Batch Spray Cleaning System

ZETA™ +

Mfg:TEL Manufacturing and Engineering of America

Features

Compact footprint with full automation	占用空间小且全自动化
Available for 200/300mm (full auto),100/150/200mm (semi auto)	适用200/300mm（全自动），100/150/200mm（半自动）
Up to 8 point of use chemicals and 1 recirculated chemistry	多达8种化学品和1种可循环使用的化学品
High temperature SPM ViPR™ process enables processing at ~220°C on wafer	高温SPM ViPR™工艺可在~220°C晶圆上进行处理

Applications

FEOL wet steps, implanted photoresist strips and metal silicide strips	FEOL湿法步骤、植入式光刻胶剥离和金属硅化物剥离
Aqueous BEOL wet steps	水基FEOL湿法步骤
Si/SiC/AlTiC/Glass/Sapphire	Si/SiC/AlTiC/玻璃/蓝宝石

单片极低温清洗设备
Single Wafer CryoKinetic Cleaning System

ANTARES™

Mfg:TEL Manufacturing and Engineering of America

Features

High fall-on particle removal efficiency	微小颗粒的高效去除性能
Uses no water or wet chemicals	固体气溶胶清洗，无需使用纯水或化学品
Will not etch or corrode metals	防止清洗过程中对金属的刻蚀及腐蚀
Will not etch or alter film properties	防止清洗过程中对薄膜性能的损坏
Ideal for hydrophobic films	适用疏水性薄膜的清洗

Applications

Post DC probe	DC探针后的清洗
Post FEOL High-k	FEOL High-k膜成膜后的清洗
Post BEOL dielectric, Low-k	BEOL绝缘膜、Low-k膜成膜后的清洗
Post BEOL CMP	BEOL化学机械研磨后的清洗
Post BEOL RIE	BEOL刻蚀后的颗粒去除清洗

涂布显影设备
Coater/Developer

CLEAN TRACK™ ACT™ 8Z

Features

- 100%兼容ACT™8的工艺转移
  100% process transfer compatible from ACT™8
- 采用300mm制程技术（全新光刻胶供应系统、超声波流量计）
  Back-engineering of 300mm process technology (New resist supply system, Ultrasonic flow meter)
- 维保性能改进（搬送手臂、自动数据备份等）
  Improved maintenance performance (Handling arm, Automatic data backup etc)

制造：TOKYO ELECTRON九州
Mfg:Tokyo Electron Kyushu

Apps

- 适用工艺：i - line、KrF、ArF、SOG/SOD、PI
  Available process; i-line, KrF, ArF, SOG/SOD, PI
- 支持多样化的晶圆衬底/尺寸：Si、SiC、GaN、玻璃、InP等/50~200mm
  Available substrate / size: Si, SiC, GaN, Glass, InP etc. / 50~200mm

清洗设备
Scrubber System

NS300+ 200mm Conversion

Features

- 配备碳化硅薄膜晶圆，实现高生产效率
  High productivity with function of SiC thin Wafer
- 先端清洗工艺技术
  Advanced scrubber process technology
- 机器与工艺数据管理系统
  Machine and process data management system

制造：TOKYO ELECTRON九州
Mfg:Tokyo Electron Kyushu

Apps

- 正面背面和斜面清洗
  Front·Backside cleaning/Bevel processing function
- 可适用150mm和200mm晶圆
  Available for 150 and 200 mm wafer
- 支持SMIF Pod/OHT处理
  SMIF pod applicable load ports/OHT applicable
- 适用多样化晶圆材料与规格
  Supports a wide variety and spec of wafer materials
- 可使用化学制剂进行化学机械研磨后的清洗
  Post CMP cleaning with light chemical
- 支持碳化硅薄型晶圆的高速传送
  High transport function of SiC thin wafer

气团束工艺设备

Gas Cluster Beam System/Corrective Etch/Trim

UltraTrimmer Plus™

Mfg:TEL Manufacturing and Engineering of America Inc.

Features

- 实现目标厚度和频率、高保真度的晶圆外形
  Reach targeted thickness and frequency wafer profile with high fidelity
- 采用GCB进行超光滑表面平整处理
  Super smooth surface flattening by GCB
- 超薄表面改造功能
  Ultra-thin surface modification function
- 基于厚度和频率的要求，进行气团式离子束调节
  Beam irradiation control based on thickness and frequency data
- 理想的室温工艺
  Ideal room temperature process
- 在不改变机械结构的情况下，可处理100、150和200mm中两个尺寸的晶圆
  Enabling two of 100, 150 and 200mm wafer size handling without mechanical change

Apps

- 射频滤波器（SAW、BAW及FBAR）的厚度与频率微调
  RF Filters (SAW, BAW and FBAR) thickness and frequency trimming
- MEMS器件及光掩模的表面平整化
  Surface flattening on MEMS device and photo mask

立式扩散/低压化学气相沉积/原子层沉积设备

Vertical Diffusion/LP-CVD/ALD Furnace System

ALPHA-8SE™ i

制造：TOKYO ELECTRON TECHNOLOGY SOLUTIONS
Mfg:Tokyo Electron Technology Solutions

Features

- 更换全新的零件、单元和组件，延长使用寿命
  Renewed parts, units, and components for life extension
- 原子层沉积工艺能力：HfO_2、Al_2O_3、SiO_2、AlN、TiO_2等
  ALD process capability: HfO_2, Al_2O_3, SiO_2, AIN, TiO_2 and so on
- 适用远程工具管理的高级监控功能
  Advanced monitoring function for remote tool management

Apps

- 扩散、低压化学气相沉积和原子层沉积
  Diffusion, LP-CVD, and ALD
- 适用150mm和200mm晶圆
  Available for 150 and 200mm wafer

等离子蚀刻设备
Plasma Etch System

UNITY™ Me+

Features

- 未改变UNITY™ Me的工艺反应腔室的设计，更新主控制器/传送机器人
  Update the main controller and transfer robot without changing the design of the UNITY™ Me process chambers
- 实现UNITY™ Me+与UNITY™ Me之间的工艺配方兼容
  Realize the process recipe compatibility between UNITY™ Me+ and UNITY™ Me
- 可以从UNITY™ Ⅱ e进行工艺追踪
  Process trace from UNITY™ II e is also possible

Apps

- 刻蚀层：电介质薄膜、SiC/Si
  Etch layer: Dielectric, SiC/Si
- 支持100、150、200mm晶圆
  100, 150, 200mm wafer applicable

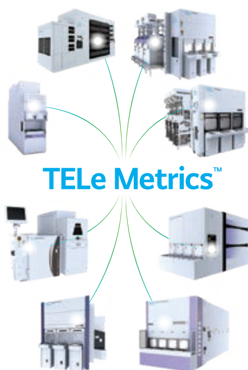
制造：TOKYO ELECTRON宫城
Mfg:Tokyo Electron Miyagi

TELeMetrics™远程设备技术服务
TELeMetrics™ Remote/Support Service

TELeMetrics™

Features

- 基于设备数据远程连接的服务
  Services based on remote access to equipment data
- 监控设备运行与警报，进行早期原因分析并采取整改措施
  Monitor equipment status and alarms, quickly analyze causes and take corrective action
- 多角度分析设备数据，提供针对性的解决方案
  Multifaceted analysis of equipment data and provision of solutions tailored to the issues
- 通过专用网络实现安全通信
  Secure communication via a dedicated network



Apps

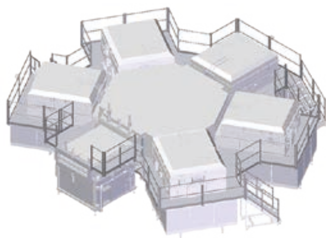
- 远程故障排除
  Remote Troubleshooting
- 警报诊断
  Alarm Diagnosis
- 生产损失分析
  Production loss analysis
- 机台差异匹配
  Machine difference matching
- 设备状态诊断
  Equipment status diagnosis

FPD刻蚀/灰化设备
FPD Etch/Ash System

Betelex™

Features

- 多反应腔室设备：多达5个工艺反应腔室
  Multi-chamber system
  5 chamber maximum
- 腔室模式：PICP™，ECCP
  Mountable units:
  PICP™, ECCP
- 基板尺寸：G6，G6Half，G8，G8Half
  Substrate size:
  G6, G6Half, G8, G8Half



制造：TOKYO ELECTRON TECHNOLOGY SOLUTIONS
Mfg:Tokyo Electron Technology Solutions

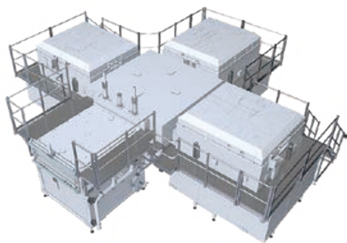
Apps

- 硅层刻蚀
  Silicon layer etch
- 绝缘层刻蚀
  Insulating layer etch
- 金属层刻蚀
  Metal layer etch
- 灰化
  Photoresist ash

Impressio™

Features

- 多反应腔室设备：多达3个工艺反应腔室
  Multi-chamber system
  3 chamber maximum
- 腔室模式：PICP™，ECCP
  Mountable units: PICP™, ECCP
- 基板尺寸：G8，G8Half，G10.5
  Substrate size: G8, G8Half, G10.5



制造：TOKYO ELECTRON TECHNOLOGY SOLUTIONS
Mfg:Tokyo Electron Technology Solutions

Apps

- 硅层刻蚀
  Silicon layer etch
- 绝缘层刻蚀
  Insulating layer etch
- 金属层刻蚀
  Metal layer etch
- 灰化
  Photoresist ash

TEL PRODUCT LINE-UP

www.tel.com/product/

Japanese

English

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Published in Japan 2025.12 | PR1 63-0120